

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a TO-263 surface mountable plastic package intended for use in applications requiring good bidirectional blocking voltage and high inrush current capability, high thermal cycling performance and high junction temperature capability ($T_{j(max)} = 150$ °C).

2. Features and benefits

- Good bidirectional blocking voltage capability
- High current surge capability
- High thermal cycling performance
- Surface mountable package
- Planar passivated for voltage ruggedness and reliability
- High junction operating temperature capability ($T_{j(max)} = 150$ °C)

3. Applications

- Capacitive Discharge Ignition (CDI)
- Crowbar protection
- Inrush protection
- Motor control
- Voltage regulation
- High junction operating temperature capability ($T_{j(max)} = 150$ °C)

4. Quick reference data

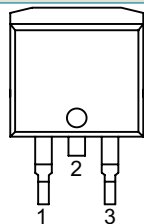

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values	Unit
Absolute maximum rating				
V_{RRM}	repetitive peak reverse voltage		650	V
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 136$ °C; Fig. 1 ; Fig. 2 ; Fig. 3	12	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25$ °C; $t_p = 10$ ms; Fig. 4 ; Fig. 5	120	A
		half sine wave; $T_{j(init)} = 25$ °C; $t_p = 8.3$ ms	132	A
T_j	junction temperature		150	°C

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 7	-	-	5	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_j = 25\text{ °C}$; Fig. 9	-	-	20	mA
V_T	on-state voltage	$I_T = 12\text{ A}$; $T_j = 25\text{ °C}$; Fig. 10	-	1.14	1.4	V
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 402\text{ V}$; $T_j = 150\text{ °C}$; $R_{GK} = 100\ \Omega$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform;	200	1000	-	V/ μ s

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		 sym037
2	A	anode		
3	G	gate		
mb	A	mounting base; connect to anode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
TYN12B-600LT	TO-263	TYN12B-600J	Reel	800	TO-263E	26-May-2017

7. Marking

Table 4. Marking codes

Type number	Marking codes
TYN12B-600LT	TYN12B-600LT

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{DRM}	repetitive peak off-state voltage		650	V
V_{RRM}	repetitive peak reverse voltage		650	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 136\text{ °C}$;	7.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 136\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3	12	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5	120	A
		half sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 8.3\text{ ms}$	132	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; sine wave	72	A^2s
di_T/dt	rate of rise of on-state current	$I_G = 10\text{ mA}$	50	$A/\mu s$
I_{GM}	peak gate current		2	A
V_{GM}	peak gate voltage		5	V
P_{GM}	peak gate power		5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	0.5	W
T_{stg}	storage temperature		-40 to 150	$^{\circ}C$
T_j	junction temperature		150	$^{\circ}C$

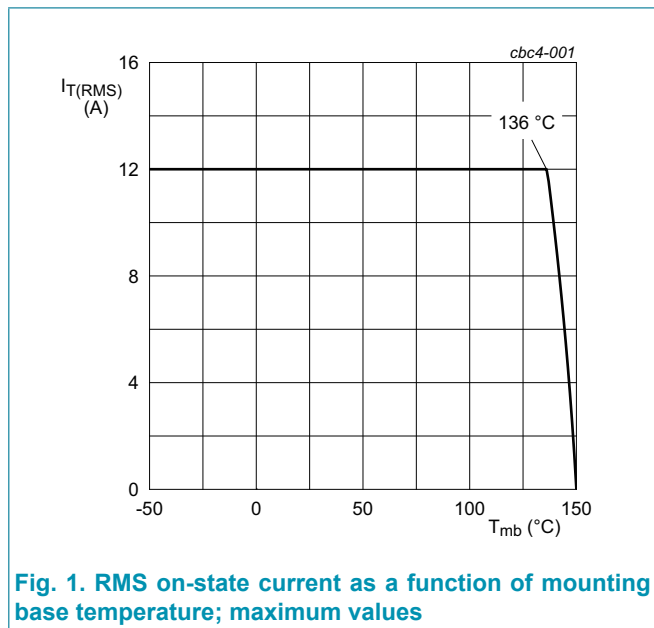


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

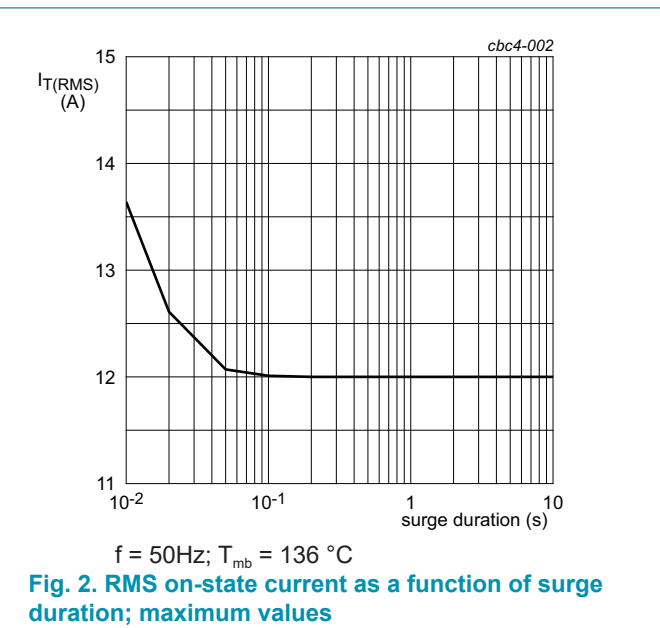


Fig. 2. RMS on-state current as a function of surge duration; maximum values

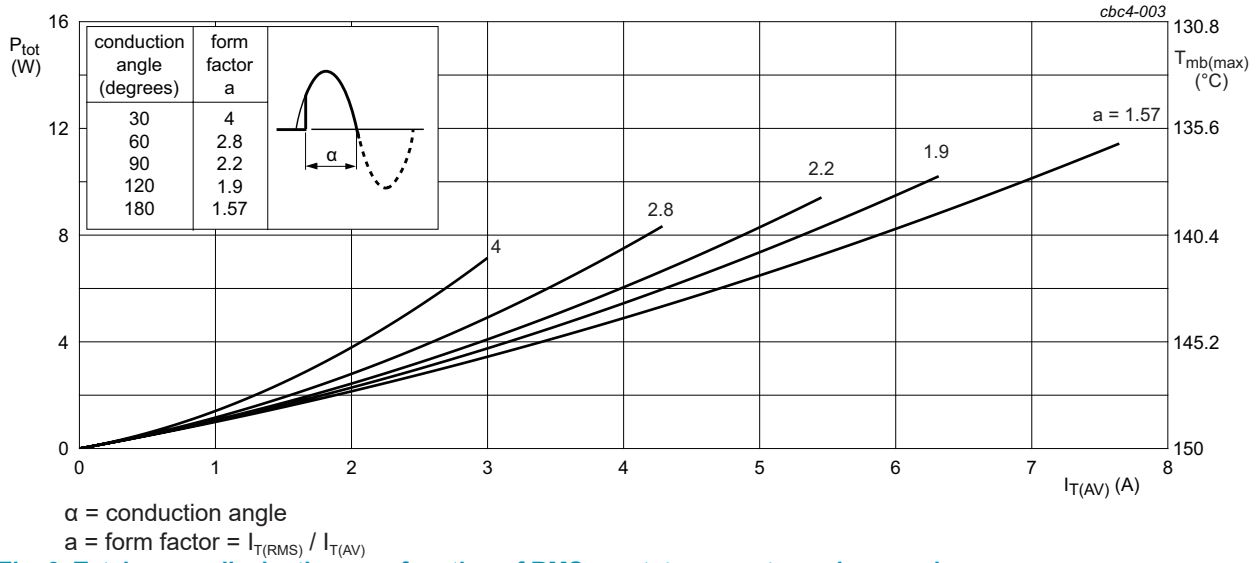


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

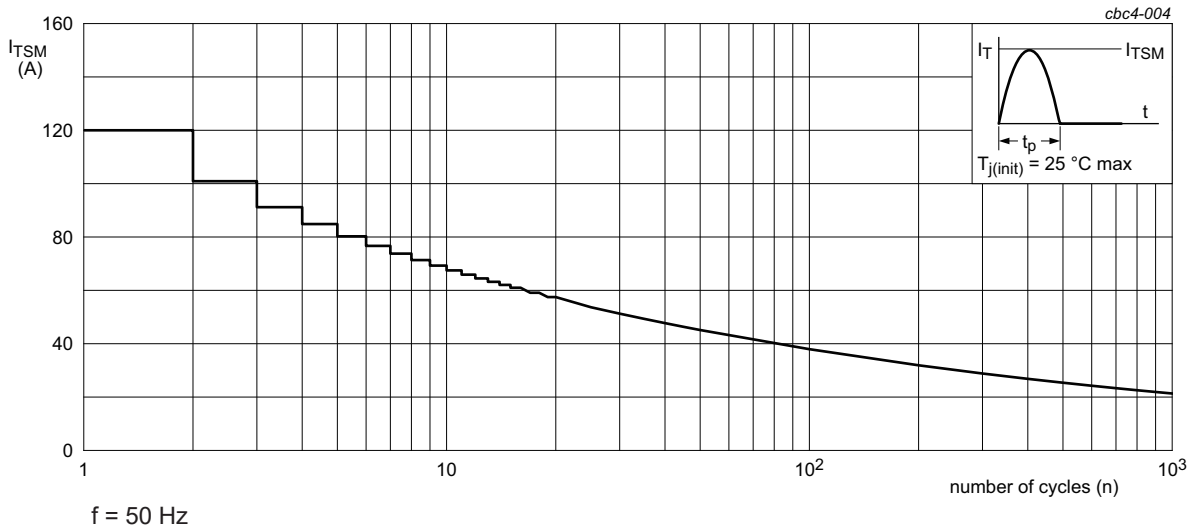


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

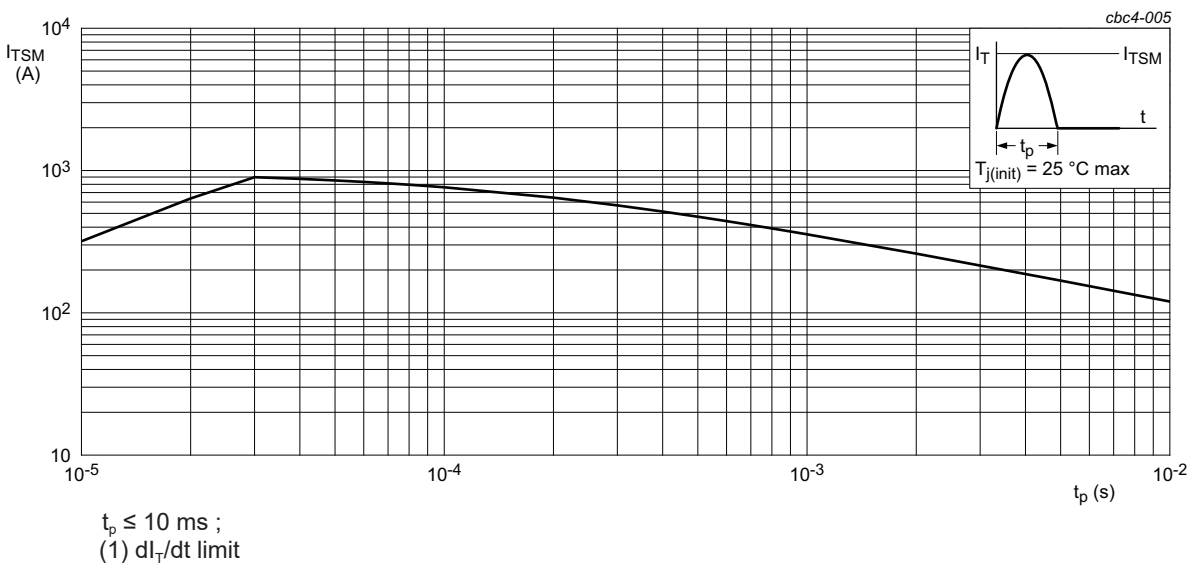


Fig. 5. Total power dissipation as a function of RMS on-state current; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6	-	-	1.2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	minimum footprint, FR4 board	-	55	-	K/W

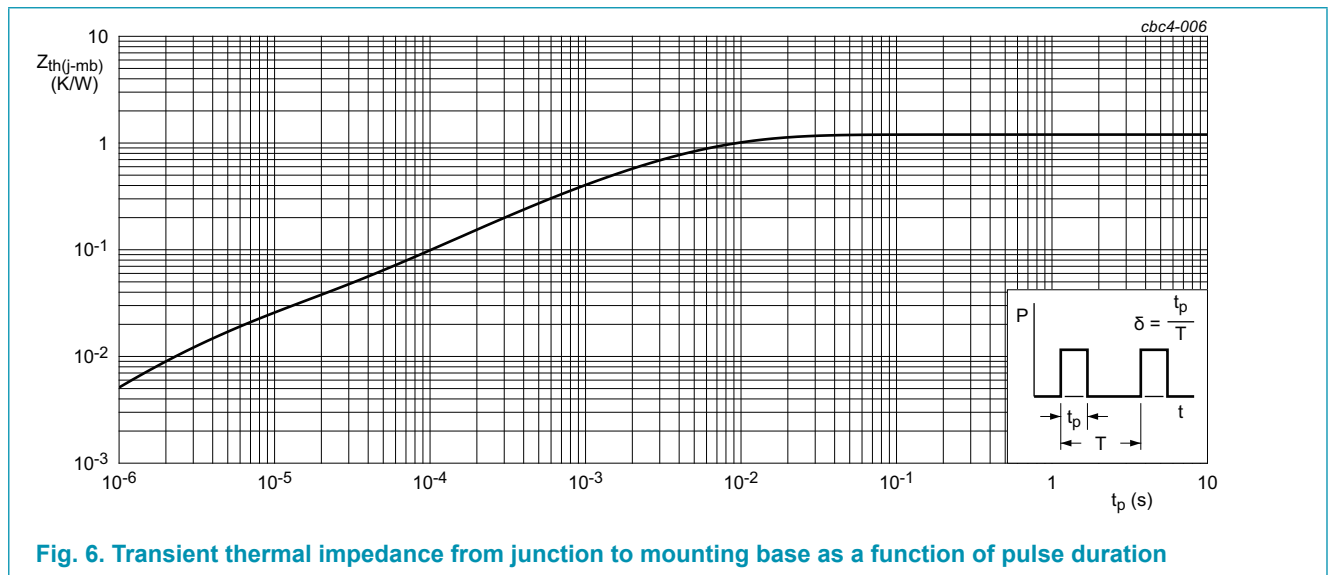
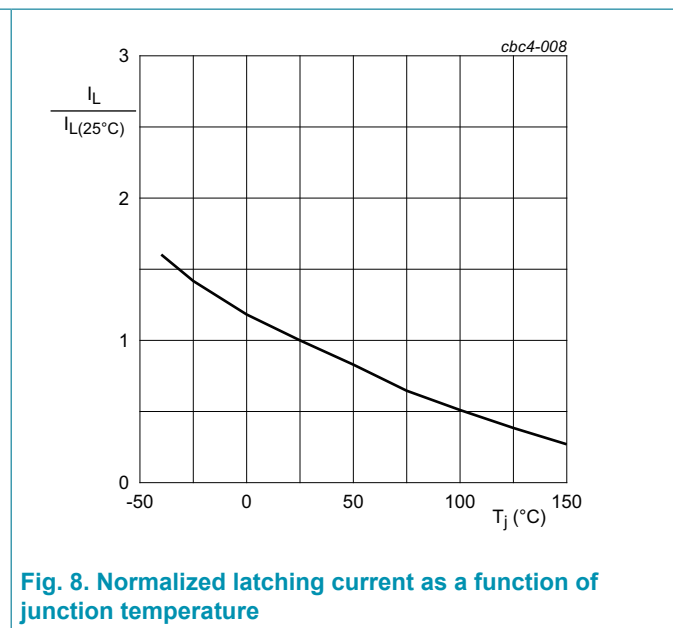
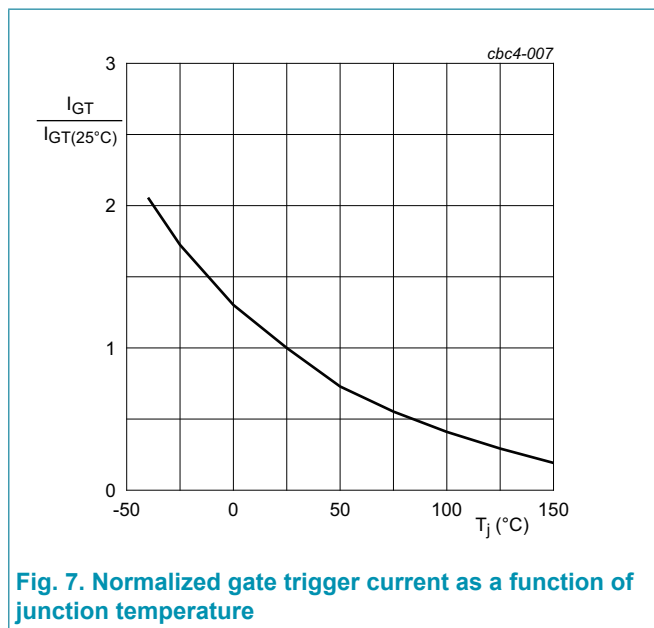


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_j = 25\text{ }^\circ\text{C}$; Fig. 7	-	-	5	mA
I_L	latching current	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_j = 25\text{ }^\circ\text{C}$; Fig. 8	-	-	40	mA
I_H	holding current	$V_D = 12\text{ V}; T_j = 25\text{ }^\circ\text{C}$; Fig. 9	-	-	20	mA
V_T	on-state voltage	$I_T = 12\text{ A}; T_j = 25\text{ }^\circ\text{C}$; Fig. 10	-	1.14	1.4	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}; I_T = 0.1\text{ A}; T_j = 25\text{ }^\circ\text{C}$; Fig. 11	-	0.7	1	V
		$V_D = 400\text{ V}; I_T = 0.1\text{ A}; T_j = 150\text{ }^\circ\text{C}$; Fig. 11	0.25	0.4	-	V
I_D	off-state current	$V_D = 650\text{ V}; T_j = 150\text{ }^\circ\text{C}$	-	-	1	mA
I_R	reverse current	$V_D = 650\text{ V}; T_j = 150\text{ }^\circ\text{C}$	-	-	1	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 402\text{ V}; T_j = 150\text{ }^\circ\text{C}; R_{GK} = 100\text{ }\Omega$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform;	200	1000	-	V/ μs
		$V_{DM} = 402\text{ V}; T_j = 150\text{ }^\circ\text{C}; (V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit	50	-	-	V/ μs
t_{gt}	gate-controlled turn-on time	$I_{TM} = 12\text{ A}; V_D = 600\text{ V}; I_G = 10\text{ mA}$; $(dI_G/dt)_M = 5\text{ A}/\mu\text{s}; T_j = 25\text{ }^\circ\text{C}$	-	2	-	μs
t_q	commutated turn-off time	$V_{DM} = 402\text{ V}; T_j = 150\text{ }^\circ\text{C}; I_{TM} = 12\text{ A}; V_R = 25\text{ V}; dV_D/dt = 30\text{ V}/\mu\text{s}; (dI_T/dt)_M = 30\text{ A}/\mu\text{s}; R_{GK(ext)} = 100\text{ }\Omega$; ($V_{DM} = 67\%$ of V_{DRM})	-	70	-	μs



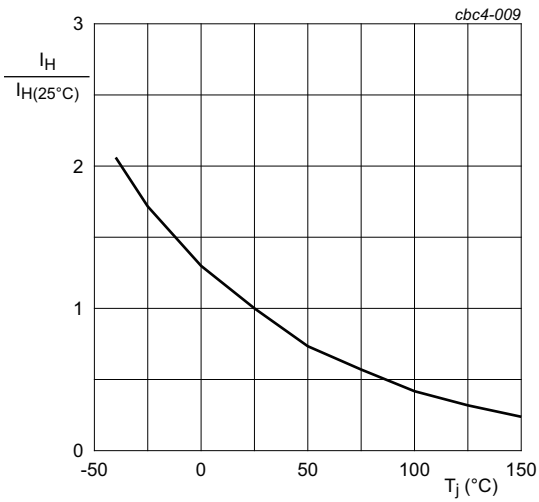
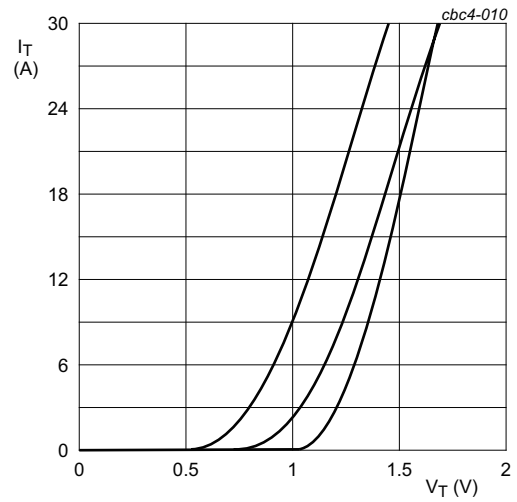


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 0.922 \text{ V}$; $R_s = 0.0304 \ \Omega$
 (1) $T_j = 150^\circ\text{C}$; typical values
 (2) $T_j = 150^\circ\text{C}$; maximum values
 (3) $T_j = 25^\circ\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

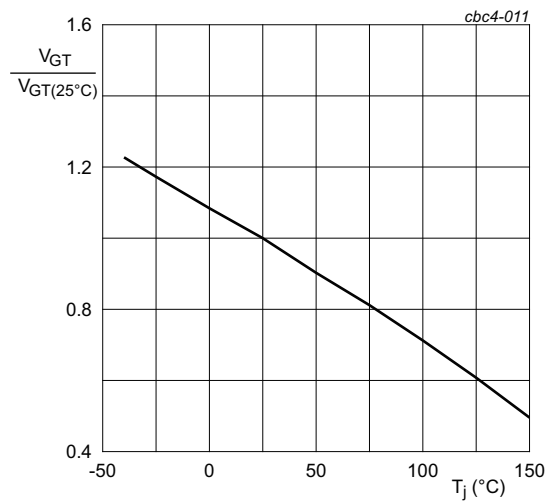
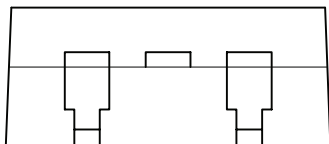
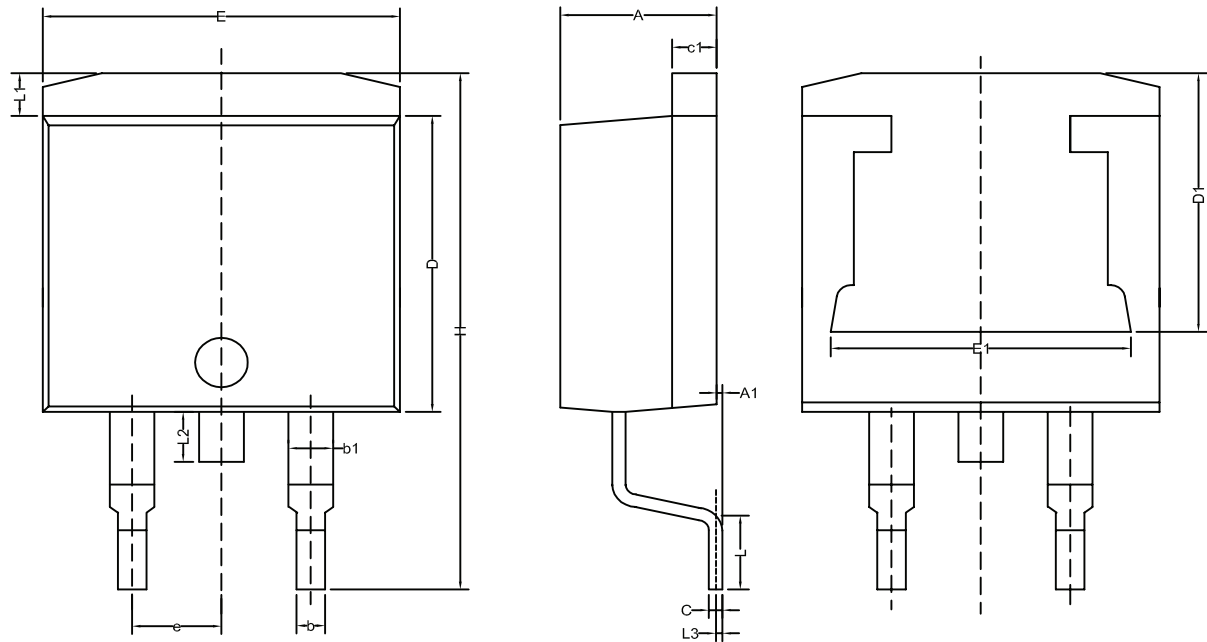


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

11. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)

TO263



Unit	A	A1	b	b1	c	c1	D	D1	E	E1	e	H	L	L1	L2	L3
MM	min	4.35	0.00	0.69	1.14	0.38	1.14	8.50	7.50	10.00	8.25	14.60	2.50	1.00	1.27	
	max	4.75	0.15	0.99	1.73	0.61	1.40	9.02	8.00	10.40	8.80	15.60	2.79	1.65	1.78	0.25
											2.54					(BSC.)

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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